

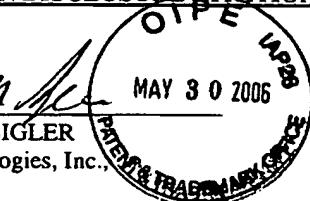
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Atty. Docket No.	Serial No.
DP-308286	10/643043

Applicant
BRANDENBURG et al.

Filing Date	Group
August 18, 2003	2811 2824

U.S. PATENT DOCUMENTS

Exam. Init.	Document Number	Date	Name	Class	Sub Class	Filing Date (if approp.)
PN	2001/026957	04-10-2001	Atwood et al.			
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	2003/134454	17-07-2003	Houle			
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Document Number	Date	Country	Class	Subclass	Translation Yes No
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19722357	19-11-1998	DE			No
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MASSALSKI T B: "Binary Alloy Phase Diagrams" BINARY ALLOY PHASE DIAGRAMS. AC-AU to FE-RH, OHIO, AMERICAN SOCIETY FOR METALS, US, vol. VOL. 1, 1986, Pages 268, 270-271, XP002177614 *Page 270*
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Copy of EP Search Report dated 20-Mar-2006

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